



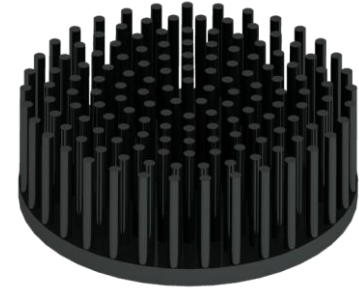
LED

GooLED

GooLED-OSR-8630 Pin Fin Heat Sink Φ 86.5mm for Osram

Features VS Benefits

- * The GooLED-OSR-8630 Osram Pin Fin LED Heat Sinks are specifically designed for luminaires using the Osram LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1,200 to 3,200 lumen.
- * Thermal resistance range R_{th} 2.5°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Osram LED engines.
- * Diameter 86.5mm - standard height 30.0mm, Other heights on request.
- * Forged from highly conductive aluminum.

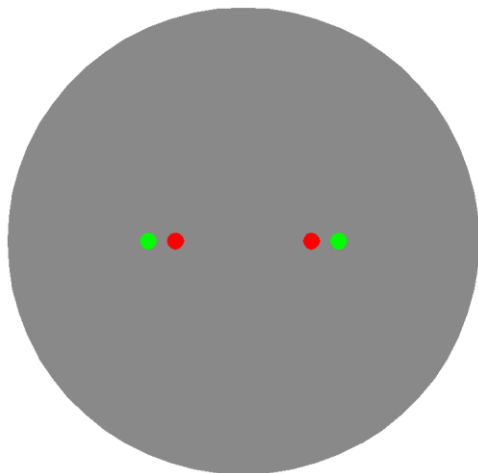


Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Osram COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

OSRAM

Opto Semiconductors



Osram LED Modules directly Mounting Options

Osram SOLERIQ® S 19 COB LED modules name:

GW KAHLxx.xx;
GW KAHQxx.xx;

With the Zhaga Book 3 Holders:

BJB holder:47.319.2170.50;
TE LED Holder:2213407-1;

Direct mounting with machine screws M3x6.5mm, green indicator marks.

With the LEDiL products:

Lenins series: CN14xxx; CN13xxx; CN12xxx;

Osram SOLERIQ® S 13 COB LED modules name:

GW KAGGxx.xx; GW KAGLxx.xx;
GW KAGHxx.xx; GW KAGMxx.xx;
GW KAGJxx.xx;

With the Zhaga Book 3 Holders:

BJB holder:47.319.2021.50;
TE LED Holder:2213254-1;

Direct mounting with machine screws M3x6.5mm, green indicator marks.

With the LEDiL products:

Lenins series: CN14xxx; CN13xxx; CN12xxx;
Ronda series: FN15xxx-xx;

Osram PrevaLED Core Z5, Z6, Style, Z7 L15 H1 and AC PRO LED modules name:

PL-CORE-Z5 -3000-xxx; PL-CORE-G7 3000-xxx L15 H1;
PL-CORE-Z5 -5000-xxx; PL-CORE-G7 5000-xxx L15 H1;
PL-CORE-Z6 -3000-xxx; PL-CORE AC PRO -2000-xxx;
PL-CORE-Z6 -5000-xxx; PL-CORE AC PRO -3000-xxx;
PL-CORE-Z4 -3000-S32;

With the Zhaga Book 3 standard:

Direct mounting with machine screws M3x6.5mm, green indicator marks.

Osram PrevaLED Core Z6 Mini LED modules name:

PL-CORE-Z6-MINI -2000-xxx;
PL-CORE-Z6-MINI -3000-xxx;

With the Zhaga Book 11 standard:

Direct mounting with machine screws M3x6.5mm, Red indicator marks.

Mounting Options and Drawings & Dimensions

Example:GooLED-OSR-8630-B-1,2

Example:GooLED-OSR-86 **1** - **2** - **3**

1 Height (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

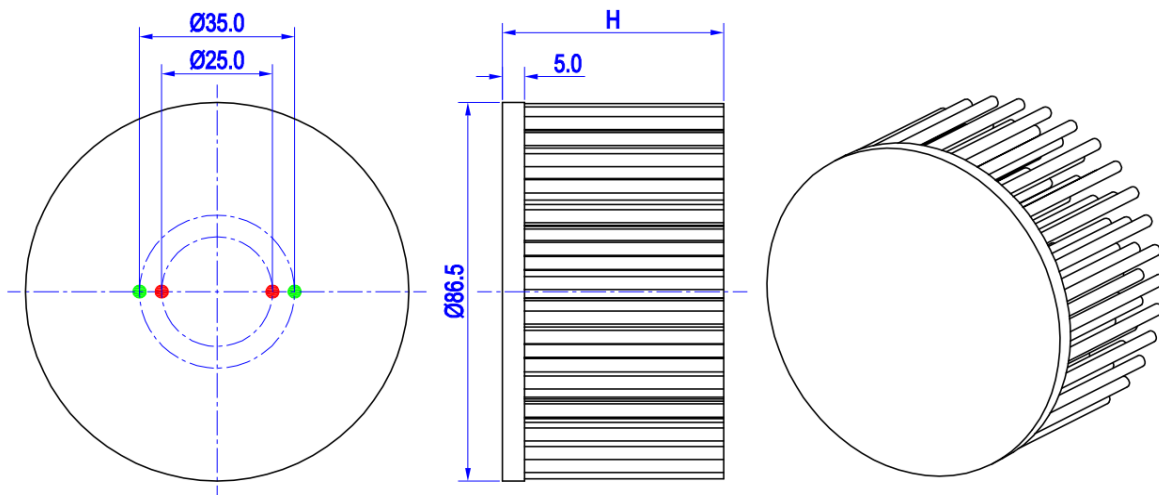
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Lenina series	Ronda series			
N	/	None	None	None	None	None	None
1	Z6 Mini	/	/	/	M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
2	Z5; Z6; Style; Z7 L15 H1; AC PRO;	/	/	/	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
	SOLERIQ® S 13	BJB Holder 47.319.2021.50 TE Holder 2213254-1	CN14xxx; CN13xxx; CN12xxx;	FN15xxx-xx			
	SOLERIQ® S 19	BJB Holder 47.319.2170.50	/	/			
		TE Holder 2213407-1	/	/			





for


LED



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GooLED-OSR-8630 Pin Fin Heat Sink Φ 86.5mm for Osram

The product data table

	Model No.	GooLED-OSR-8630
	Heatsink Size	Φ 86.5xH30mm
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	152.0
	Dissipated power (T _{hs-amb} ,50°C)	20.0 (W)
	Cooling surface area (mm ²)	48926
	Thermal Resistance (R _{hs-amb})	2.5 (°C/W)

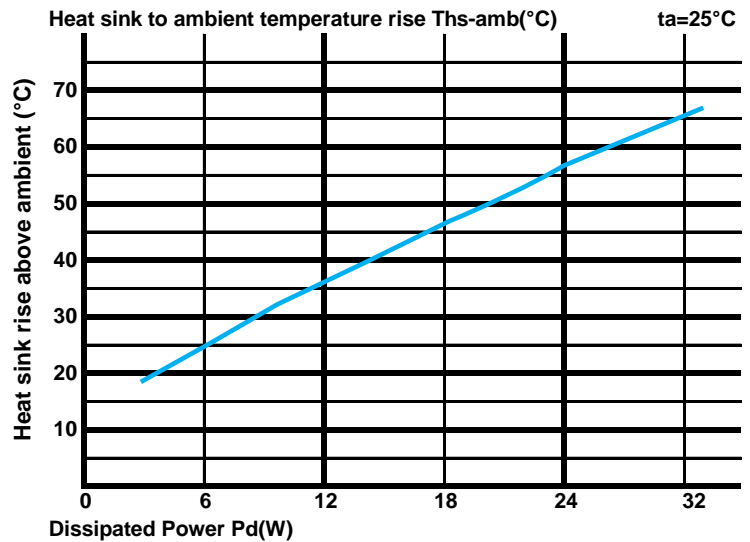
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

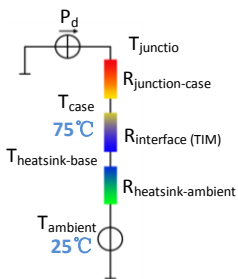
Dissipated Power Pd(W)	Pd = Pe x (1-ηL)	Heat sink to ambient thermal resistance R _{hs-amb} (°C/W)	Heat sink to ambient temperature rise T _{hs-amb} (°C)
		GooLED-OSR-8630	
6.0		4.00	24.0
12.0		2.92	35.0
18.0		2.56	46.0
24.0		2.33	56.0
32.0		2.03	65.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W]; T_{hs} - Heatsink temperature; T_a - Ambient temperature;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R_{junction-case}, the thermal resistance of the TIM outside the package is R_{interface (TIM)} [°C/W], the thermal resistance with the heat sink is R_{heatsink-ambient} [°C/W], and the ambient temperature is T_{ambient} [°C].

*Thermal resistances outside the package R_{interface (TIM)} and R_{heatsink-ambient} can be integrated into the thermal resistance R_{case-ambient} at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$